

# HSS82

Silicon Epitaxial Planar Diode for High Voltage Switching

# HITACHI

ADE-208-176A (Z)

Rev. 1

Jul. 1995

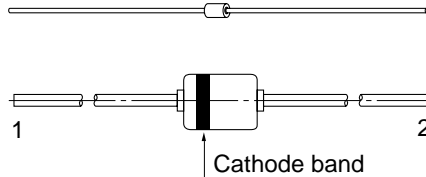
## Features

- High reverse voltage. ( $V_R = 200V$ )
- Suitable for 5mm pitch high speed automatic insertion.
- Small glass package (MHD) enables easy mounting and high reliability.

## Ordering Information

Type No.	Cathode band	Package Code
HSS82	Navy Blue	MHD

## Outline



1. Cathode
2. Anode

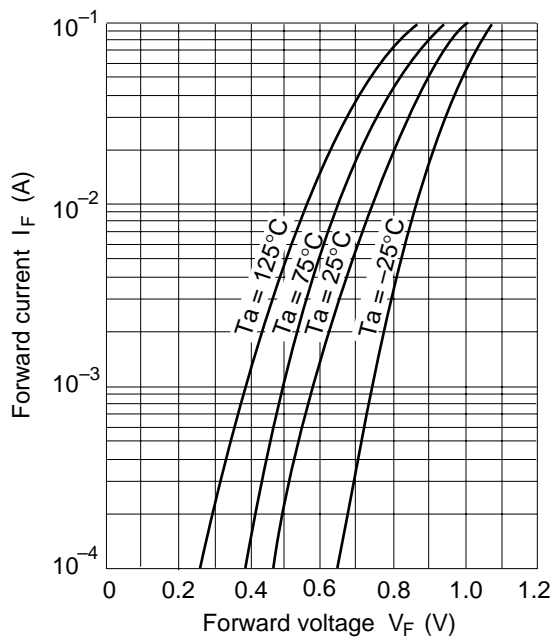
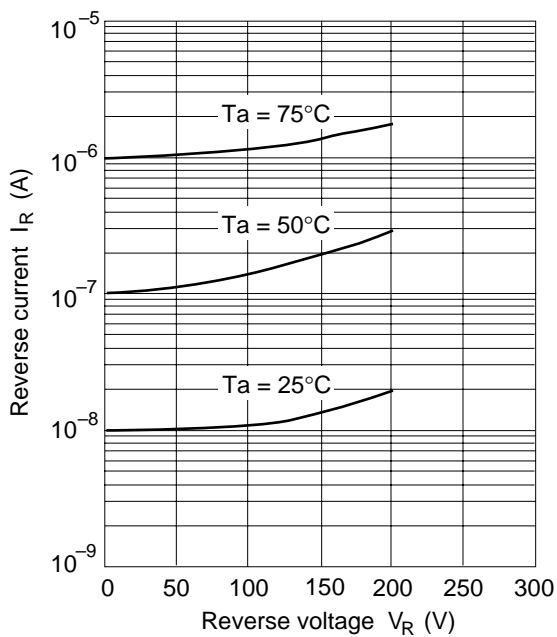
**Absolute Maximum Ratings**\*2 (Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	$V_{RM}^{*1}$	250	V
Reverse voltage	$V_R$	200	V
Peak forward current	$I_{FM}$	625	mA
Non-Repetitive peak forward surge current	$I_{FSM}^{*2}$	1	A
Average forward current	$I_O$	150	mA
Power dissipation	Pd	400	mW
Junction temperature	Tj	200	°C
Storage temperature	Tstg	-65 to +175	°C

Notes: 1. Reverse voltage in excess of peak reverse voltage may deteriorate electrical characteristic.  
2. Within 1s forward surge current.

**Electrical Characteristics** (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	$V_F$	—	—	1.0	V	$I_F = 100\text{mA}$
Reverse current	$I_{R1}$	—	—	0.2	$\mu\text{A}$	$V_R = 200\text{V}$
	$I_{R2}$	—	—	100		$V_R = 250\text{V}$
Capacitance	C	—	1.5	—	pF	$V_R = 0\text{V}$ , $f = 1\text{MHz}$
Reverse recovery time	$t_{rr}$	—	—	100	ns	$I_F = I_R = 30\text{mA}$ , $I_{rr} = 3\text{mA}$ , $R_L = 100\Omega$

**Fig.1 Forward current Vs. Forward voltage****Fig.2 Reverse current Vs. Reverse voltage**

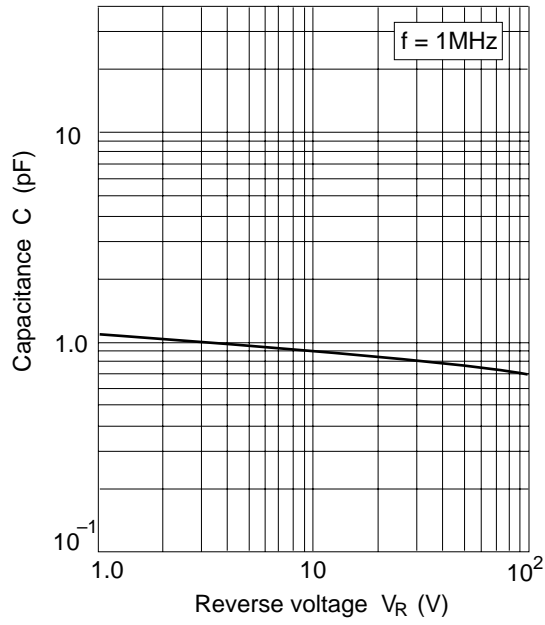
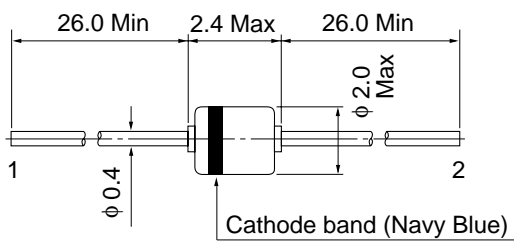


Fig.3 Capacitance Vs. Reverse voltage

Package Dimensions

Unit: mm



1 Cathode  
2 Anode

HITACHI Code	MHD
JEDEC Code	DO-34
EIAJ Code	—
Weight (g)	0.084

## Cautions

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